09-05-2003



U.S. Department of Commerce Patents & Trademark Office

`	102542919	Attorney Docket No. 103203-00007 Date: August 29, 2003			
-	To the Assistant Commissioner of Patents  Please record the attached original documents or copy thereof				
	1. Name of conveying party(ies)  Tadao NAKAOKA Akitoshi SUZUKI Hideo OTSUKA Hisao KIMIJIMA  Additional name(s) of conveying party(ies) attached?  Yes No  3. Nature of conveyance:  Assignment Merger Security Agreement Change of Name Other  Execution Date: August 19, 2003 (all parties)	2. Name and address of receiving party(ies):  Name: FURUKAWA CIRCUIT FOIL CO., LTD  Address: 8-9, Kandanishiki-cho 1-chome, Chiyoda-ku, Tokyo 101-0054 JAPAN  Additional name(s) & address(es) attached?			
	4. Application number(s) or patent number(s):  If this document is being filed together with a new application, the execution date of the application is: August 19, 2003 (all parties)  A. Patent Application No.(s)  B. Patent No.(s)  Additional numbers attached? ☐ Yes ☑ No				
	Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved:     One			
	Name: Arent Fox Kintner Plotkin & Kahn PLLC	7. Total fee (37 CFR 3.41) \$ 40.00			
	Street Address: 1050 Connecticut Avenue, N.W., Suite 400	☐ Included in attached check.			
	Washington, D.C. 20036-5339	Any additional fees are authorized to be charged to deposit account			
9.	03/2003 MBELETE1 00000010 10651099 FC:8021 40.00 OP	Deposit account number: 01-2300     (Attach duplicate copy of this page if paying by deposit account)			
	DO NOT USE TH	IIS SPACE			
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.  Charles M. Marmelstein  Name of Person Signing  Signature  August 29, 2003  Date					
Reg. No. 25,895 CMM/jch Total number of pages including cover sheet, attachments, and document: 2					

## U.S. ASSIGNMENT

WHEREAS:				
Tadao NAKAOKA, Akitoshi SUZUKI, Hideo OTSUKA and Hisao				
KIMIJIMA whose full post office address(es) is/are,				
c/o FURUKAWA CIRCUIT FOIL CO., LTD				
601-2, Otorozawa, Imaichi-city, Tochigi-ken 321-2336 Japan,				
(hereinafter referred to as ASSIGNOR), has/have invented				
certain new and useful improvements in an invention				
entitled:				
COPPER FOIL FOR CHIP-ON-FILM USE, PLASMA DISPLAY PANEL, OR				
HIGH-FREQUENCY PRINTED CIRCUIT BOARD				
(a) for which an application for United States Letters				
Patent is being executed and filed concurrently herewith;				
(b) for which an application for United States Letters				
Patent was executed on;				
(c) for which an application for United States Letters				
Patent was filed on,				
Serial No;				
(d) for which an PCT International application was filed				
on				
as International application No				
WHEREAS:				
FURUKAWA CIRCUIT FOIL CO., LTD				
8-9, Kandanishiki-cho 1-chome, Chiyoda-ku, Tokyo 101-0054				
<u>Japan</u>				
(hereinafter referred to as ASSIGNEE), is desirous of				
acquiring the entire interest in, to and under said				
invention and in, to and under Letters Patent or similar				

legal protection to be obtained therefor in the United

States and in any and all foreign countries.

PATENT REEL: 014463 FRAME: 0173 NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt and sufficiency of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE, its lawful successors and assigns, the full and exclusive right, title and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, division, continuation-in-part, reexamination, renewal, substitute, extension or reissue thereof or any legal equivalent thereof in a foreign country for the full term or terms for which the same may be granted; and authorize and request the Commissioner of Patent of the United States and any official of any foreign country whose duty it is to issue patents of legal equivalents thereto, to issue same for this invention to ASSIGNEE, its lawful successors and assigns.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof in any foreign country which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/WE have hereunto set hand and signed on the date indicated below:

DATE SIGNED

INVENTOR (S)

		<del> </del>
1) Jadaa Nakaako	- Aug. 19, 2003	Ikira Matsuda
Tadao NAKAOKA		
2) Akitoshi Siyu	li <u>Aug. 19, 2003</u>	Akira Matsuda
Akitoshi SUZUKI	<b>y</b>	

PATENT REEL: 014463 FRAME: 0174

WITNESS (ES)

3) Hideo Otenka	Aug. 19, 2003	Upira Matsuda
Hideo OTSUKA	<i>(</i>	-
4) Kisao Kimijima	Aus 19.2003	akira Matsuda

Hisao KIMIJIMA

**RECORDED: 08/29/2003** 

PATENT REEL: 014463 FRAME: 0175